

Technical information : THERMAL DISPENSING

Description:

Thermal paste is directly dispensed on casting or PCB for **thermal dissipation**. The dispensing of the paste uses a 3 axes digitally controlled, which allows to adapt the thickness of the paste deposition, to be adapted to the equipment topography.

Material	Loaded silicone, different viscosities and thermal conductivities
Manufacturing processes	Automatic dispense on the equipment by our programmable robot
Packaging	Syringe, Pot, Cartridge
Options	We supply the only material
Prototyping	-

Properties		Unit		Product	Test Method
Physical properties	Specific Gravity	-		2.8 to 3.2	ASTM D792
	Viscosity	Pa-s	1.0 (1/s)	600 to 4,100	ASTM D1824
			0.5 (1/s)	1,000 to 6,900	
	Weight loss	wt%		0.02 to 0.06	ASTM D412
Consistency	-		170 to 430	ASTM D1403	
Electrical properties	Volume resistivity	Ohm-m		1x10 ¹²	ASTM D257
	Dielectric constant	50Hz / 1KHz / 1MHz		10.95 to 14.85	ASTM D150
	Dissipation factor	50Hz / 1KHz / 1MHz		0.0003 to 0.0032	ASTM D150
Thermal properties	Thermal conductivity	W/mK		2.0 to 5.0	By Hot Disk
	Recommended operating temp.	°C		-40 to +150	-
		°F		-40 to +302	-
Extratable volatiles	wt% (D ₂₄ to D ₂₀)		0.0010 to 0.0043	Gas chromatography	